

JEDEC SOLID STATE  
PRODUCT OUTLINE  
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THIS *STANDARD OUTLINE* HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

TITLE PLASTIC DUAL SMALL  
OUTLINE, 1.27MM PITCH, 7.50MM BODY  
WIDTH, RECT FAMILY PACKAGE

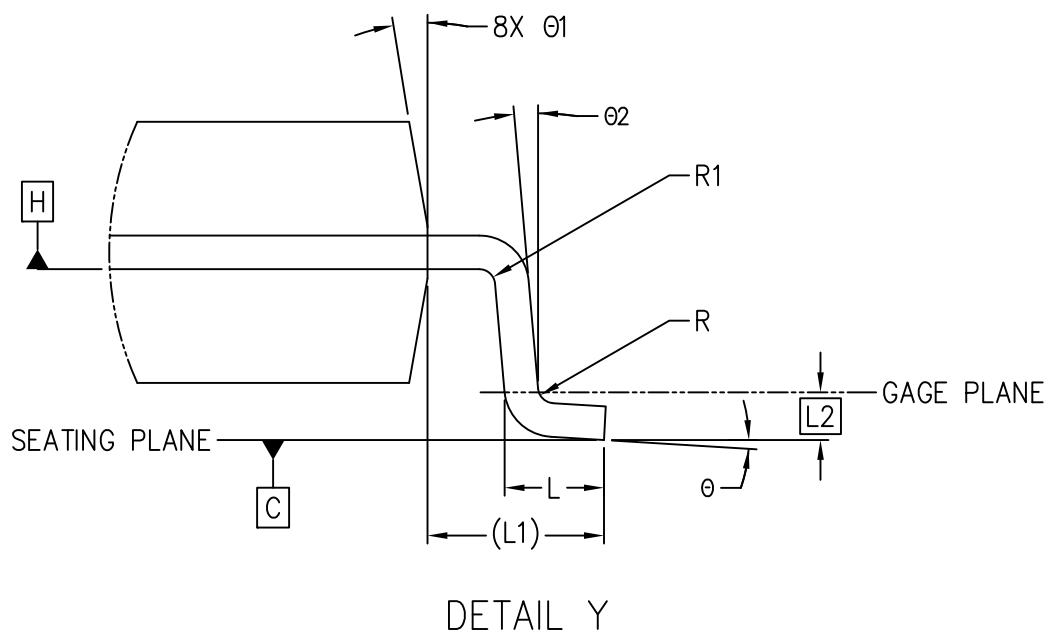
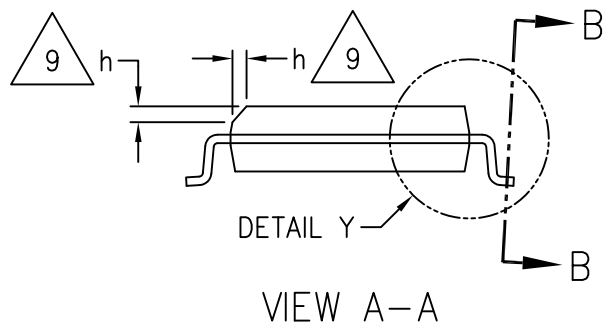
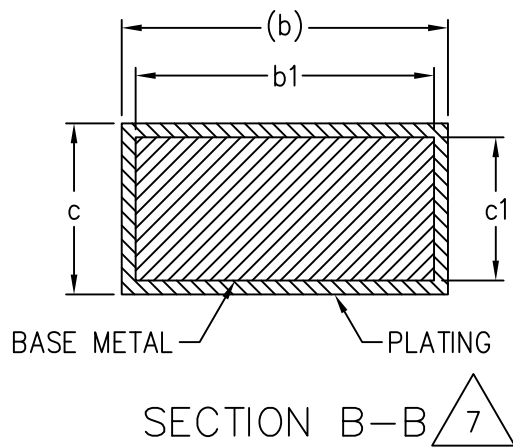
PACKAGE DESIGNATOR  
PDSO-G#\_1p27...

NUMBER  
MS-013

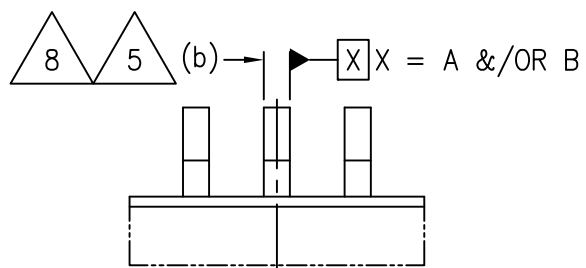
ISSUE  
G

DATE  
NOV 2020

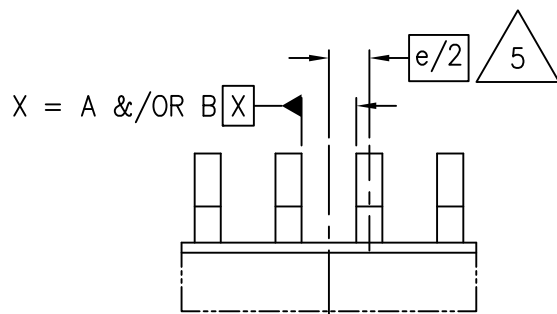
SHEET  
1 OF 6



ODD LEADS  
PER SIDE



EVEN LEADS  
PER SIDE



DETAIL Z

TABLE 1

COMMON DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A2	2.05	----	----	
b	0.31	----	0.51	7, 8
b1	0.27	----	0.48	7, 8
c	0.10	----	0.33	7
c1	0.10	----	0.30	7
E	10.30 BASIC			
E1	7.50 BASIC			3, 4
e	1.27 BASIC			
L	0.40	----	1.27	
L1	1.40 REF			
L2	0.25 BASIC			
R	0.07	----	----	
R1	0.07	----	----	
h	0.25	----	0.75	9
θ	0°	----	8°	
θ1	5°	----	15°	
θ2	0°	----	----	
NOTES	1, 2			
REF	11-720S, 11-910S			
ISSUE	F			

TABLE 2

TOLERANCE OF FORM AND POSITION		
SYMBOL	VALUE	
aaa	0.10	---
bbb	0.33	---
ccc	0.10	---
ddd	0.25	---
eee	0.10	---
fff	0.20	---
ggg	0.15	---
NOTES	1, 2	
REF	11-720S	
ISSUE	E	

TABLE 3

STANDARD VARIATIONS									
VARIATION ►		AA	AB	AC	AD	AE	AF	AG	NOTES
SYMBOL ▼									
A	MIN	---							
	NOM	---							
	MAX	2.65							
A1	MIN	0.10							10
	NOM	---							
	MAX	0.30							
D BASIC		10.30	11.55	12.80	15.40	17.90	9.00	5.85	3, 4
N		16	18	20	24	28	14	8	6
NOTES		---							
REF		11–720S, 11–967S							
ISSUE		G							

TABLE 4

THERMAL VARIATIONS															
VARIATION ►		BA		BB		BC		BD		BE		BF		NOTES	
SYMBOL ▼															
A	MIN	---													
	NOM	---													
	MAX	2.50													
A1	MIN	0.00												10	
	NOM	---													
	MAX	0.15													
D BASIC		10.30	11.55	12.80	15.40	17.90	9.00	3, 4							
D1	MIN	3.00												11	
	NOM	---													
	MAX	---													
E2	MIN	2.00												11	
	NOM	---													
	MAX	---													
N		16	18	20	24	28	14	6							
NOTES		---													
REF		11–720S													
ISSUE		E													

# NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5-2009.

2. ALL DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).



DIMENSION 'D' DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER END. DIMENSION 'E1' DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 MM PER SIDE. 'D' AND 'E1' DIMENSIONS ARE DETERMINED AT DATUM H.



THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONS "D" AND 'E1' ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS, AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.



DATUMS A & B TO BE DETERMINED AT DATUM H.

6. 'N' IS THE MAXIMUM NUMBER OF TERMINAL POSITIONS FOR THE SPECIFIED PACKAGE LENGTH.



THE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 TO 0.25 MM FROM THE LEAD TIP.



DIMENSION 'b' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.10 MM TOTAL IN EXCESS OF THE 'b' DIMENSION MAXIMUM MATERIAL CONDITION. THE DAMBAR MAY NOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.



THIS CHAMFER FEATURE IS OPTIONAL. IF IT IS NOT PRESENT, THEN A PIN 1 IDENTIFIER MUST BE LOCATED WITHIN THE INDEX AREA INDICATED



'A1' IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY EXCLUDING THE LID AND OR THERMAL ENHANCEMENT ON CAVITY DOWN PACKAGE CONFIGURATIONS.



'D1' AND 'E2' MINIMUM DIMENSIONS OF THERMALLY ENHANCED TYPES ARE VARIABLES DEPENDING ON DEVICE FUNCTION (DIE PADDLE SIZE). 'D1' AND 'E2' MAXIMUM DIMENSIONS CAN BE EQUAL TO 'D' AND 'E1' MAXIMUM DIMENSIONS. END USER SHOULD VERIFY ACTUAL SIZE OF EXPOSED THERMAL PAD FOR SPECIFIC DEVICE APPLICATION.

STP (3D) FILE RECORD  
3D FILE NAMES MAY EXCEED LENGTH REQUIREMENTS FOR SOME SOFTWARE TOOLS.

STP FILE NAME	ISSUE	DATE	ITEM NUMBER
PDS0-G8_l1p27-R5p85x7p5Z2p65-N10p3C#T0p33	G	NOV 2020	11-967S

TASK GROUP CONTRIBUTORS

ON SEMICONDUCTOR

# CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE: –	DATE: –	JC11 ITEM NUMBER: –
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CHANGE RECORD HISTORY:
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ISSUE: E	DATE: SEPTEMBER 2005	ITEM NUMBER: 11–720S
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LOCATION:	CHANGED FROM:	CHANGED TO:
PAGE 1, BOTTOM VIEW	TOP VIEW, SIDE VIEW	ADD BOTTOM VIEW TO SHOW EXPOSED THERMAL PAD ZONE
PAGE 3, VARIATION TABLE	6 NON-THERMAL OPTIONS AA TO AF	ADD 6 THERMAL OPTIONS BA TO BF

ISSUE: F	DATE: JANUARY 2016	ITEM NUMBER: 11–910S
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LOCATION:	CHANGED FROM:	CHANGED TO:
ALL SHEETS		REDRAWN & UPDATED TO CURRENT FORMAT STANDARDS: DIMENSIONS, TEXT HEIGHT, TABLES, ETC. NOTHING ADDED OR DELETED BUT SOME DIMENSIONS/TEXT MAY HAVE MOVED
SHEET 3, TABLE 1	C & C1 = 0.20 MIN	C & C1 = 0.10 MIN
SHEET 6, NOTE 1	ASME Y15.4–1994	ASME Y14.5–2009

ISSUE: G	DATE: NOVEMBER 2020	ITEM NUMBER: 11–967S
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LOCATION:	CHANGED FROM:	CHANGED TO:
ALL SHEETS, TITLE	VERY THICK PROFILE PLASTIC SMALL OUTLINE FAMILY 1.27 MM PITCH, 7.50 MM BODY WIDTH	PLASTIC DUAL SMALL OUTLINE 1.27 MM PITCH, 7.50 MM BODY WIDTH. RECT FAMILY PACKAGE
SHEET 1, PACKAGE DESIGNATOR	B1R–PDSO/SOP/SOIC	PDSO–G#_I1p27...
SHEET 4, TABLE 3		ADDED VARIATION AG